Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!

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Bulletin PD-20755 rev. E 05/06

International
IOR Rectifier

MBRD650CT
MBRD660CT

SCHOTTKY RECTIFIER

6 Amp

$I_{F(AV)}$ = 6.0Amp
V_R = 50-60V

Major Ratings and Characteristics

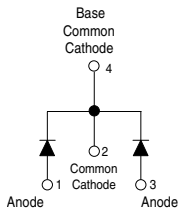
Characteristics		Values	Units
$I_{F(AV)}$	Rectangular waveform	6	A
V_{RRM}		50 - 60	V
I_{FSM}	@ tp = 5 µs sine	490	A
V_F	@3 Apk, T_J = 125°C (per leg)	0.65	V
T_J	range	- 40 to 150	°C

Description/ Features

The MBRD650CT, MBRD660CT surface mount, center tap, Schottky rectifier series has been designed for applications requiring low forward drop and small foot prints on PC board. Typical applications are in disk drives, switching power supplies, converters, free-wheeling diodes, battery charging, and reverse battery protection.

- Popular D-PAK outline
- Center tap configuration
- Small foot print, surface mountable
- Low forward voltage drop
- High frequency operation
- Guard ring for enhanced ruggedness and long term reliability

Case Styles



D-PAK (TO-252AA)

Voltage Ratings

	Part number	MBRD650CT	MBRD660CT
V_R	Max. DC Reverse Voltage (V)	50	60
V_{RWM}	Max. Working Peak Reverse Voltage (V)		

Absolute Maximum Ratings

	Parameters	Value	Units	Conditions	
$I_{F(AV)}$	Max. Average Forward (Per Leg)	3.0	A	50% duty cycle @ T_C = 128°C, rectangular wave form	
	Current * See Fig. 5 (Per Device)	6			
I_{FSM}	Max. Peak One Cycle Non-Repetitive	490	A	5µs Sine or 3µs Rect. pulse	Following any rated load condition and with rated V_{RRM} applied
	Surge Current * See Fig. 7	75		10ms Sine or 6ms Rect. pulse	
E_{AS}	Non-Repet. Aval. Energy (Per Leg)	6	mJ	T_J = 25 °C, I_{AS} = 1 Amp, L = 12 mH	
I_{AR}	Repetitive Avalanche Current (Per Leg)	0.6	A	Current decaying linearly to zero in 1 µsec Frequency limited by T_J max. V_A = 1.5 x V_R typical	

Electrical Specifications

	Parameters	Value	Units	Conditions	
V_{FM}	Max. Forward Voltage Drop	0.7	V	@ 3A	T_J = 25 °C
	(Per Leg) * See Fig. 1 (1)	0.9	V	@ 6A	
		0.65	V	@ 3A	T_J = 125 °C
		0.85	V	@ 6A	
I_{RM}	Max. Reverse Leakage Current	0.1	mA	T_J = 25 °C	V_R = rated V_R
	(Per Leg) * See Fig. 2 (1)	15	mA	T_J = 125 °C	
C_T	Typ. Junction Capacitance (Per Leg)	145	pF	V_R = 5V_{DC} (test signal range 100Khz to 1Mhz) 25°C	
L_S	Typical Series Inductance (Per Leg)	5.0	nH	Measured lead to lead 5mm from package body	
dv/dt	Max. Voltage Rate of Change	10000	V/µs	(Rated V_R)	

(1) Pulse Width < 300µs, Duty Cycle <2%

Thermal-Mechanical Specifications

	Parameters	Value	Units	Conditions
T_J	Max. Junction Temperature Range (*)	-40 to 150	°C	
T_{stg}	Max. Storage Temperature Range	-40 to 150	°C	
R_{thJC}	Max. Thermal Resistance (Per Leg)	6	°C/W	DC operation * See Fig. 4
	Junction to Case (Per Device)	3		
R_{thJA}	Max. Thermal Resistance Junction to Ambient	80	°C/W	
wt	Approximate Weight	0.3 (0.01)	g (oz.)	
	Case Style	D-Pak		Similar to TO-252AA
	Device Marking	MBRD660CT		

(*) $\frac{dPtot}{dTj} < \frac{1}{Rth(j\text{-}a)}$ thermal runaway condition for a diode on its own heatsink

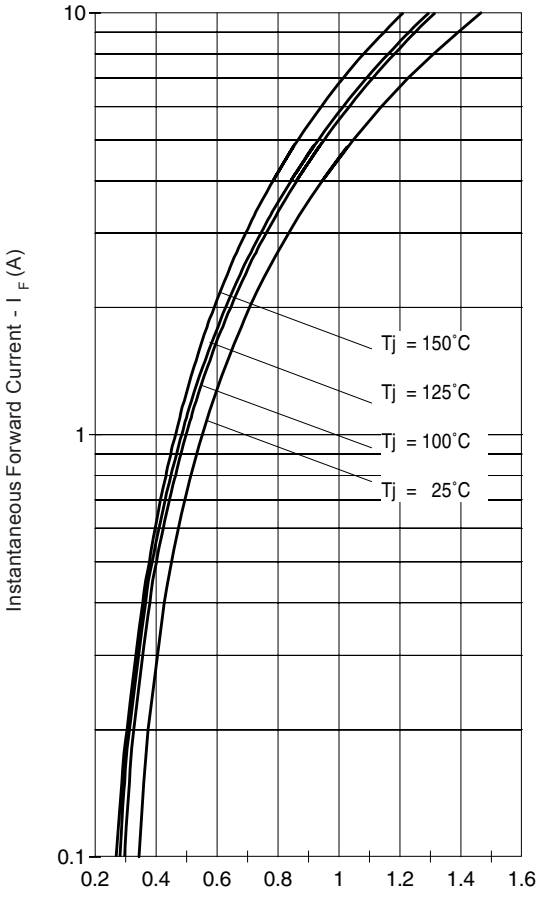


Fig. 1 - Max. Forward Voltage Drop Characteristics (Per Leg)

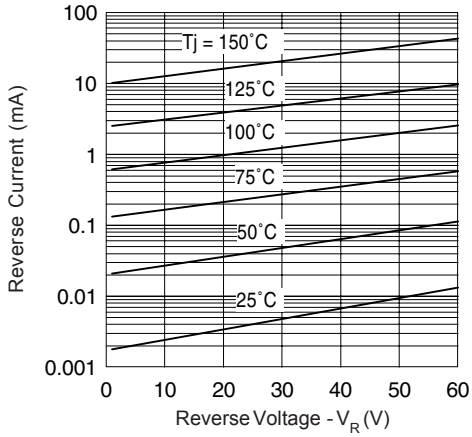


Fig. 2 - Typical Values Of Reverse Current Vs. Reverse Voltage (Per Leg)

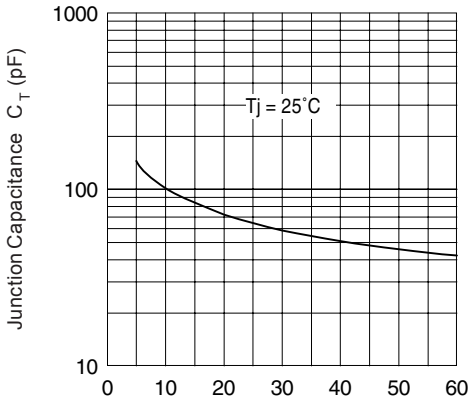


Fig. 3 - Typical Junction Capacitance Vs. Reverse Voltage (Per Leg)

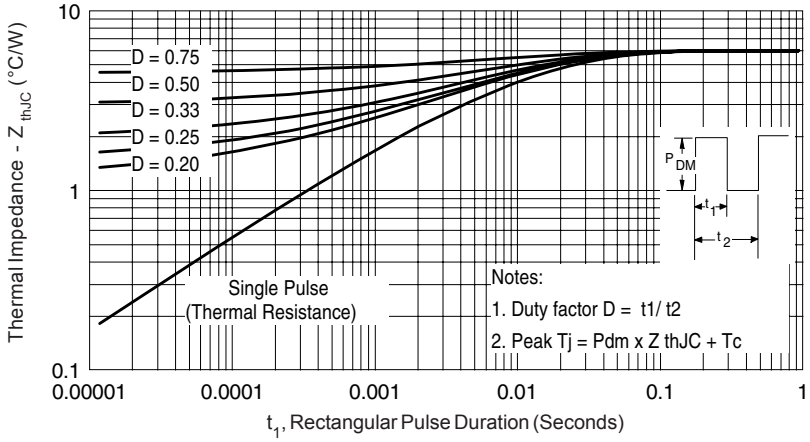


Fig. 4 - Max. Thermal Impedance Z_{thJC} Characteristics (Per Leg)

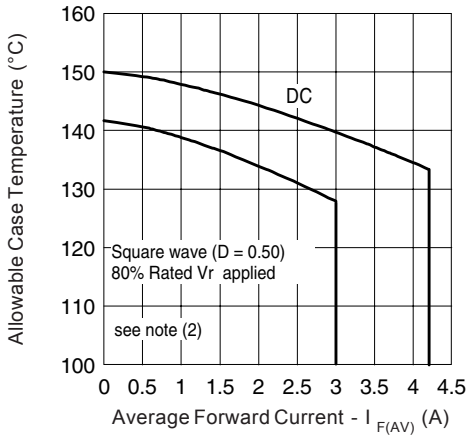


Fig. 5 - Max. Allowable Case Temperature Vs. Average Forward Current (Per Leg)

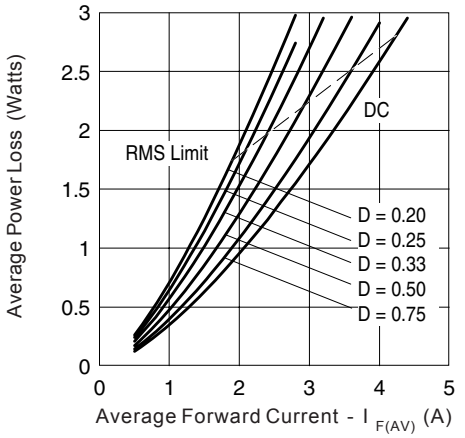


Fig. 6 - Forward Power Loss Characteristics (Per Leg)

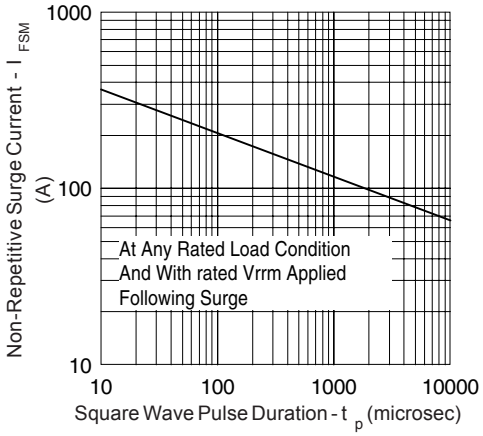
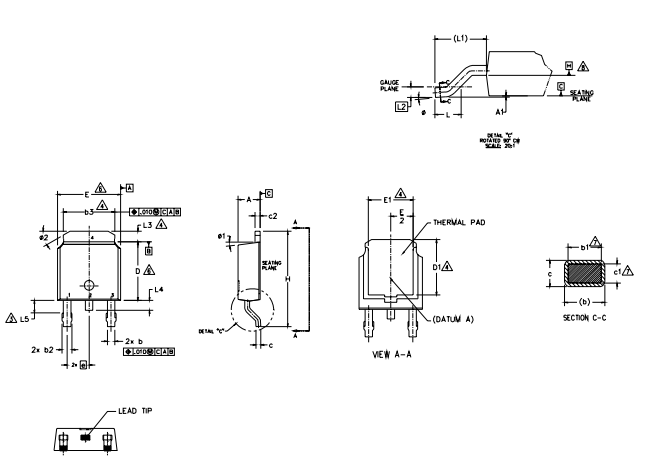


Fig. 7 - Max. Non-Repetitive Surge Current (Per Leg)

(2) Formula used: $T_C = T_J - (Pd + Pd_{REV}) \times R_{thJC}$;
Pd = Forward Power Loss = $I_{F(AV)} \times V_{FM} @ (I_{F(AV)} / D)$ (see Fig. 6);
Pd_{REV} = Inverse Power Loss = $V_{R1} \times I_R (1 - D)$; $I_R @ V_{R1}$ = 80% rated V_R

Outline Table



NOTES:
1.- DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994
2.- DIMENSION ARE SHOWN IN INCHES [MILLIMETERS].
3 LEAD DIMENSION UNCONTROLLED IN L5.
4 DIMENSION D1, E1, L3 & b3 ESTABLISH A MINIMUM MOUNTING SURFACE FOR THERMAL PAD.
5.- SECTION C-C DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN .005 AND 0.10 [0.13 AND 0.25] FROM THE LEAD TIP.
6 DIMENSION D & E DO NOT INCLUDE MOLD FLASH. MOLD FLASH SHALL NOT EXCEED .005 [0.13] PER SIDE. THESE DIMENSIONS ARE MEASURED AT THE OUTMOST EXTREMES OF THE PLASTIC BODY.
7 DIMENSION b1 & c1 APPLIED TO BASE METAL ONLY.
8 DATUM A & B TO BE DETERMINED AT DATUM PLANE H.
9.- OUTLINE CONFORMS TO JEDEC OUTLINE TO-252AA.

SYMBOL	DIMENSIONS				NOTES
	MILLIMETERS		INCHES		
	MIN.	MAX.	MIN.	MAX.	
A	2.18	2.39	.086	.094	
A1	–	0.13	–	.005	
b	0.64	0.89	.025	.035	
b1	0.65	0.79	.025	.031	7
b2	0.76	1.14	.030	.045	
b3	4.95	5.46	.195	.215	4
c	0.46	0.61	.018	.024	
c1	0.41	0.56	.016	.022	7
c2	0.46	0.89	.018	.035	
D	5.97	6.22	.235	.245	6
D1	5.21	–	.205	–	4
E	6.35	6.73	.250	.265	6
E1	4.32	–	.170	–	4
e	2.29 BSC		.090 BSC		
H	9.40	10.41	.370	.410	
L	1.40	1.78	.055	.070	
L1	2.74 BSC		.108 REF.		
L2	0.51 BSC		.020 BSC		
L3	0.89	1.27	.035	.050	4
L4	–	1.02	–	.040	
L5	1.14	1.52	.045	.060	3
ø	0°	10°	0°	10°	
ø1	0°	15°	0°	15°	
ø2	25°	35°	25°	35°	

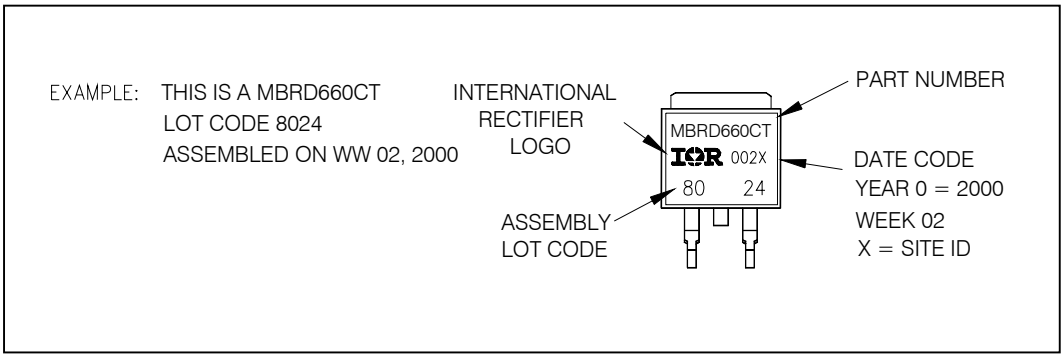
LEAD ASSIGNMENTS

HEXFET
1.- GATE
2.- DRAIN
3.- SOURCE
4.- DRAIN

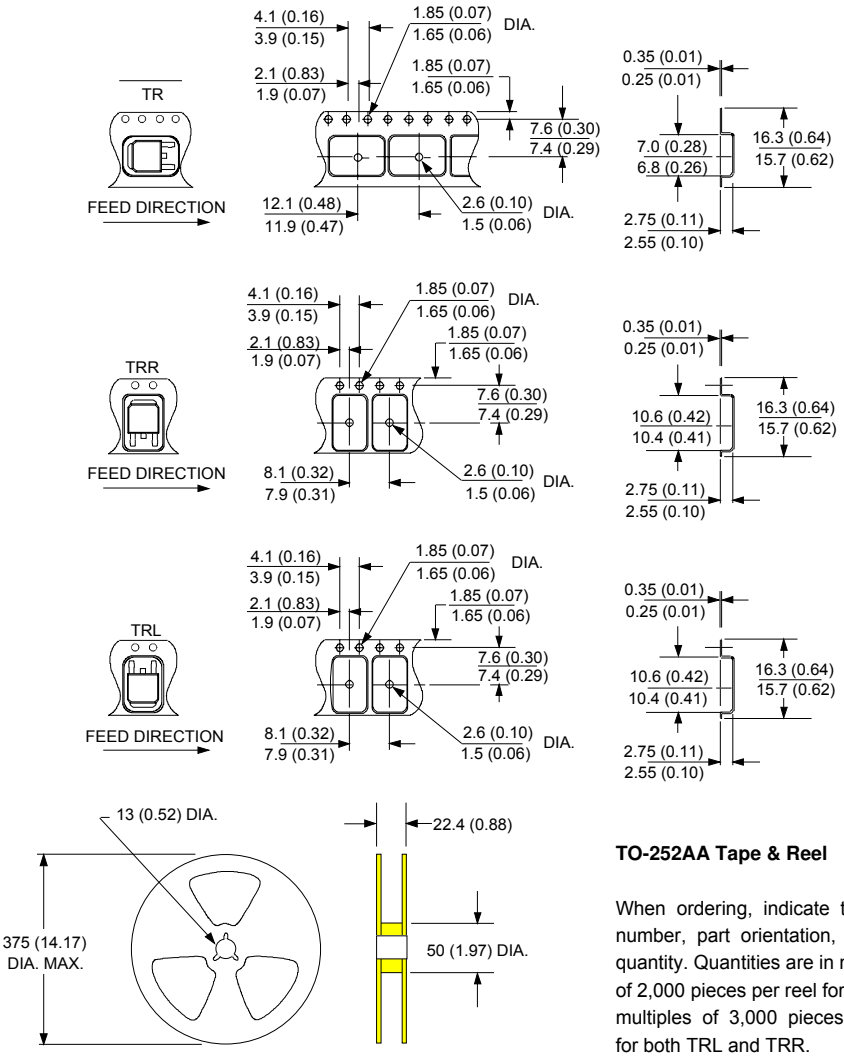
IGBT & CoPAK
1.- GATE
2.- COLLECTOR
3.- EMITTER
4.- COLLECTOR

Modified JEDEC outline TO-252AA
Dimensions in millimeters and (inches)

Part Marking Information



Tape & Reel Information

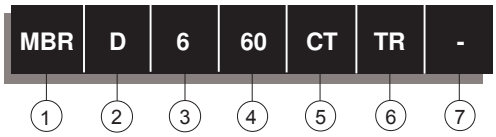


TO-252AA Tape & Reel

When ordering, indicate the part number, part orientation, and the quantity. Quantities are in multiples of 2,000 pieces per reel for TR and multiples of 3,000 pieces per reel for both TRL and TRR.

Ordering Information Table

Device Code



1	-	Schottky MBR Series
2	-	D = D-Pak (TO-252AA)
3	-	Currrent Rating (6 = 6A)
4	-	Voltage Ratings (50 = 50V, 60 = 60V)
5	-	CT = Center Tap (Dual)
6	-	• none = Tube (50 pieces) • TR = Tape & Reel • TRL = Tape & Reel (Left Oriented) • TRR = Tape & Reel (Right Oriented)
7	-	• none = Standard Production • PbF = Lead-Free

Data and specifications subject to change without notice.
This product has been designed and qualified for AEC Q101 Level.
Qualification Standards can be found on IR's Web site.

International
IOR Rectifier

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TAC Fax: (310) 252-7309
05/06

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